	lumber:	20170614003	}	PCN Date:		July 14, 20)17	
		LM5122-Q1 and LM5122					,,,	
Customer Contact:		PCN Manager			De	pt: Qua	ality Services	
hand	ge Type:						·	
	Assembly Site		Design			Wafer Bun	np Site	
	Assembly Process		Data Sheet			Wafer Bump Material		
	Assembly Material	s	Part number change			Wafer Bun	•	
Mechanical Specification		cation	Test Site			Wafer Fab		
	Packing/Shipping/	Labeling	Test Process			Wafer Fab	Materials	
						Wafer Fab	Process	
		No	tification	Details				
escr	iption of Change:							
	Instruments Incorp oduct datasheet(s)		-		locin			
c pi		is being updut						
ie fo	llowing change hist	ory provides fu	rther details.					
		, .						
	Texas							
4	INSTRUMENTS					LI	M5122-Q1	
						SNVSAW	-JUNE 2017	
Chang	es from Revision SNVS95	54G (May 2016) to R	evision *				Page	
	lit out LM5122-Q1 from the							
	bruary 2013. This document			· •				
Added links for WEBENCH Changed 20-HTSSOP Thermal Information								
	•							
• Au	ded Negative to Positive co	Inversion example					33	
	Texas Instruments						LM5122	
	INSTRUMENTS			SNVS954H	-FEBRI	UARY 2013-REVISE	D JUNE 2017	
hang	es from Revision <mark>G (</mark> May	2016) to Revision H					Page	
Cha	anged by splitting out the a	utomotive datasheet	from this commer	cial datasheet			1	
Add	ded 24-pin HTTSOP packa	ge option					1	
Add	ded links for WEBENCH						1	
Add	ded 24-HTSSOP pin config	uration					4	
Added 24-HTSSOP Functions							5	
Added LM5122Z part number							6	
Changed 20-HTSSOP Thermal Information and added 24-HTSSOP thermal values								
 Added I_{CSP} –I_{CSN} (LM5122Z only) specs 								
Added No load, 50% to 50% (LM5122Z only) specs								
Added 24-pin HTSSOP							14	
	ded Negative to Positive co							
	atasheet number wi		Change E				- T	
Jevic	e Family		Change Fron	1:		Change	e 10:	

Device Family	Change From:	Change To:
LM5122-Q1	SNVS954G	SNVSAW9
LM5122	SNVS954G	SNVS954H

These changes may be reviewed at the datasheet links provided. <u>http://www.ti.com/product/LM5122-Q1</u> <u>http://www.ti.com/product/LM5122</u>

Reason for Change:

To accurately represent the device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:									
	LM5122QMH/NOPB	LM5122QMHX/NOPB	LM5122MH/NOPB	LM5122MHE/NOPB					
	LM5122MHX/NOPB	LM5122QMHE/NOPB	LM5122ZPWPR	LM5122ZPWPT					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com